Lattice Semiconductor Corporation - LC5768VG-10F256I Datasheet

Welcome to E-XFL.COM

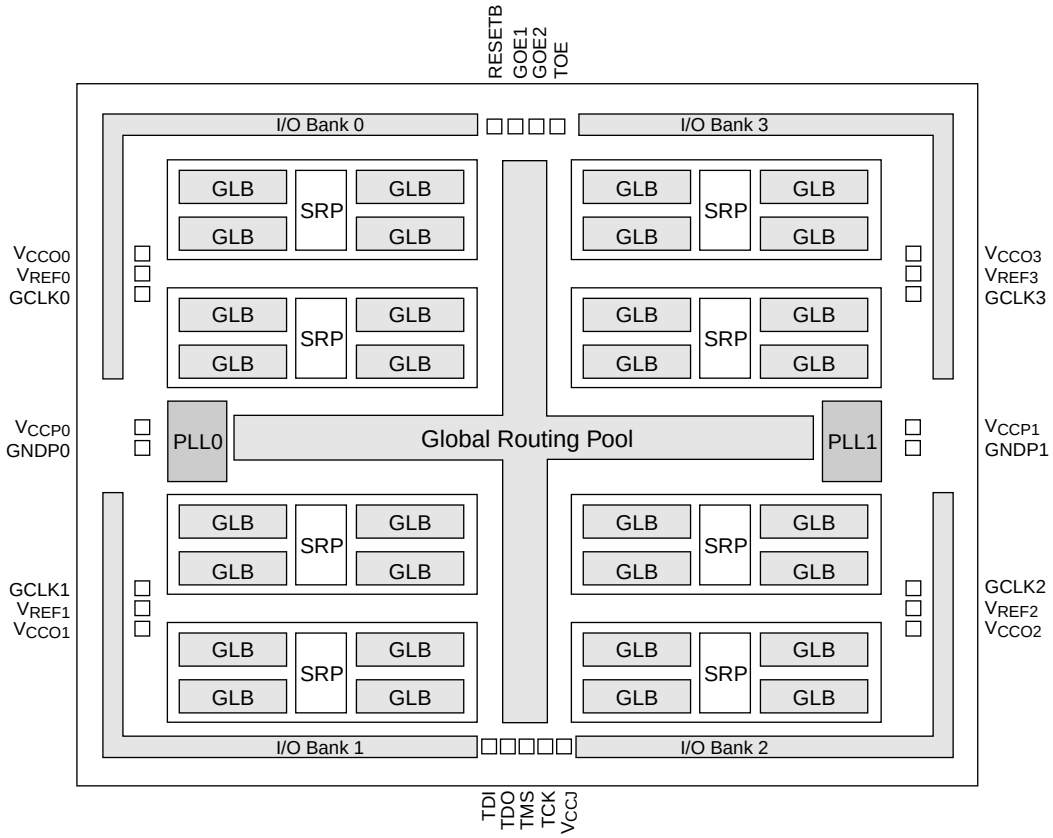
Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	24
Number of Macrocells	768
Number of Gates	-
Number of I/O	196
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5768vg-10f256i

Figure 1. Functional Block Diagram



Overview

The ispMACH 5000VG devices consist of multiple SuperWIDE 68-input, 32-macrocell Generic Logic Blocks (GLBs) interconnected by a tiered routing system. Figure 1 shows the functional block diagram of the ispMACH 5000VG. Groups of four GLBs, referred to as segments, are interconnected via a Segment Routing Pool (SRP). Segments are interconnected via the Global Routing Pool (GRP.) Together the GLBs and the routing pools allow designers to create large designs in a single device without compromising performance.

Each GLB has 68 inputs coming from the SRP and contains 163 product terms. These product terms form groups of five product term clusters, which feed the PT sharing array or the macrocell directly. The ispMACH 5000VG allows up to 160 product terms to be connected to a single macrocell via the product term expanders and PT Sharing Array.

The macrocell is designed to provide flexible clocking and control functionality with the capability to select between global, product term and block-level resources. The outputs of the macrocells are fed back into the switch matrices and, if required, the sysIO cell.

All I/Os in the ispMACH 5000VG family are sysIOs, which are split into four banks. Each bank has a separate I/O power supply and reference voltage. The sysIO cells allow operation with a wide range of today's emerging interface standards. Within a bank, inputs can be set to a variety of standards, providing the reference voltage requirements of the chosen standards are compatible. Within a bank, the outputs can be set to differing standards, providing the I/O power supply voltage and the reference voltage requirements of the chosen standard are compatible. Support for this wide range of standards allows designers to achieve significantly higher board-level performance compared to the more traditional LVCMOS standards.

The ispMACH5000VG devices also contain sysCLOCK Phase Locked Loops (PLLs) that provide designers with increased clocking flexibility. The PLLs can be used to synthesize new clocks for use on-chip or elsewhere within the system. They can also be used to deskew clocks, again both at the chip and system levels. A variable delay line capability further improves this and allows designers to retard or advance the clock in order to tune set-up and clock-to-out times for optimal results. The ispMACH 5000VG Family Selection Guide (Table 1) details the key attributes and packages for the ispMACH 5000VG devices.

ispMACH 5000VG Architecture

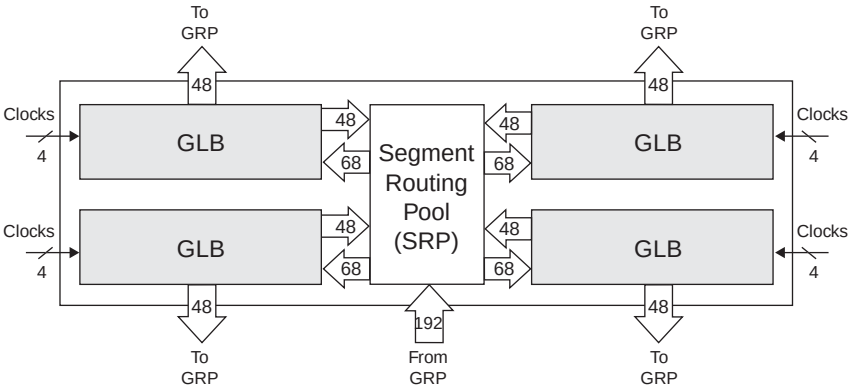
The ispMACH 5000VG Family of In-System Programmable High Density Logic Devices is based on segments containing four Generic Logic Blocks (GLBs) and a hierarchical routing pool (GRP) structure interconnecting the segments. A segment routing pool (SRP) connects each GLB in a segment allowing the maximum flexibility and speed.

Outputs from the GLBs drive the Segment Routing Pool (SRP) and the Global Routing Pool (GRP). Enhanced switching resources are provided to allow signals in the Segment Routing Pool to drive any or all the GLBs in the segment. Optimal switching is provided to allow all signals in the Global Routing Pool to be routed to any or all SRPs. This mechanism allows fast, efficient connections across the entire device.

Segment

Each segment contains four GLBs and a segment routing pool (SRP). Each GLB has 32 internal feedback outputs and 16 external feedback outputs, for a total of 48 outputs from each GLB feeding the SRP. The SRP contains up to 384 signals, 48 from each GLB and 192 from the GRP, with full routing capability. This routing scheme maximizes the flexibility and speed of the device without sacrificing the routing.

Figure 2. Segment



Generic Logic Block

Each GLB contains 32 macrocells and a fully populated, programmable AND-array with 160 logic product terms and three control product terms. The GLB has 68 inputs from the Segment Routing Pool, which are available in both true and complement form for every product term. The three control product terms are used for shared reset, clock and output enable functions. Figure 3 shows the structure of the GLB from the macrocell perspective. This is referred to as a macrocell slice. There are 32 macrocell slices per GLB.

AND-Array

The programmable AND-Array consists of 68 inputs and 163 output product terms. The 68 inputs from the SRP are used to form 136 lines in the AND-Array (true and complement of the inputs). Each line in the array can be connected to any of the 163 output product terms via a wired AND. Each of the 160 logic product terms feed the Dual-OR Array with the remaining three control product terms feeding the Shared PT Clock, Shared PT Reset and Shared PT OE. Every set of five product terms from the 160 logic product terms forms a product term cluster start-

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 5000VG devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispMACH 5000VG family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

IEEE 1532-Compliant In-System Programming

In-system programming of devices provides a number of significant benefits including rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispMACH 5000VG devices provide In-System Programming (ISP™) capability through their Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1532 standard. By using IEEE 1532 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

The ispMACH 5000VG devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispMACH 5000VG devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 5000VG devices during the testing of a circuit board.

Security Bit

A programmable security bit is provided on the ispMACH 5000VG devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary design from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Hot Socketing

The ispMACH 5000VG devices are well suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down device be minimal on active signals.

Density Migration

The ispMACH 5000 family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Absolute Maximum Ratings[1, 2, 3]

Supply Voltage (V_{CC}) . . . . . -0.5 to 5.4V

PLL Supply Voltage (V_{CCP}) . . . . . -0.5 to 5.4V

Output Supply Voltage (V_{CCO}) . . . . . -0.5 to 5.4V

Input Voltage Applied[4] . . . . . -0.5 to 5.6V

Tri-state Output Voltage Applied. . . . . -0.5 to 5.6V

Storage Temperature . . . . . -65 to 150°C

Junction Temperature (Tj) with Power Applied . . . . . -55 to 130°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and Undershoot of -2V to (V_{IH} (MAX)+2) volts is permitted for a duration of < 20ns.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V_{CC}	Supply Voltage	3.0	3.6	V
V_{CCP}	Supply Voltage for PLL block	3.0	3.6	V
V_{CCJ}	Supply Voltage for IEEE1149.1 Test Access Port	1.65	3.6	V
Tj (Commercial)	Junction Commercial Operation	0	90	C
Tj (Industrial)	Junction Industrial Operation	-40	105	C

Note: V_{CCJ} must be set in appropriate range to be compatible with desired LVCMOS standard.

Erase Reprogram Specifications

Parameter	Min	Max	Units
Erase/Reprogram Cycle	1000	—	Cycles

Hot Socketing Characteristics[1,2,3]

Symbol	Parameter	Condition	Min	Typ	Max	Units
I_{DK}	Input or I/O Leakage Current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	+/-100	µA
		V_{IH} (MAX) $\le V_{IN} \le$ 5.5V	—	—	+/-100	µA

1. Insensitive to sequence of V_{CC} and V_{CCO}. However, assumes monotonic rise / fall rates for V_{CC} and V_{CCO}.
2. LVTTL, LVCMOS only
3. $0 < V_{CC} \le V_{CC}$ (MAX), $0 < V_{CCO} \le V_{CCO}$ (MAX)

sysIO Recommended Operating Conditions[2]

Standard	V_{CCO} (V)		V_{REF} (V)	
	Min	Max	Min	Max
LVCMOS 3.3[1]	3.0	3.6	—	—
LVCMOS 2.5	2.3	2.7	—	—
LVCMOS 1.8	1.65	1.95	—	—
LVTTL	3.0	3.6	—	—
PCI 3.3	3.0	3.6	—	—
PCI-X	3.0	3.6	—	—
AGP-1X	3.15	3.45	—	—
SSTL 2	2.3	2.7	1.15	1.35
SSTL 3	3.0	3.6	1.3	1.7
CTT 3.3	3.0	3.6	1.35	1.65
CTT 2.5	2.3	2.7	1.35	1.65
HSTL	1.4	1.6	0.68	0.9
GTL+	1.4	3.6	0.882	1.122

1. Software default setting.
2. Typical values for V_{CCO} and V_{REF} are the average of the Min and Max values.

sysIO DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}[2] (mA)	I_{OH}[2] (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVCMOS 3.3[1]	-0.3	0.8	2.0	5.5	0.4	2.4	20	-20
LVCMOS 3.3	-0.3	0.8	2.0	5.5	0.4	2.4	16, 12 8, 5.33, 4	-16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	5.5	0.4	2.4	20	-20
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCO} - 0.4	16, 12, 8, 5.33, 4	-16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCO}$	$0.65V_{CCO}$	3.6	0.4	V_{CCO}-0.4	12, 8, 5.33, 4	-12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
PCI 3.3	-0.3	$0.3V_{CCO}$	$0.5V_{CCO}$	3.6	$0.1V_{CCO}$	$0.9V_{CCO}$	1.5	-0.5
PCI-X	-0.3	$0.35V_{CCO}$	$0.5V_{CCO}$	3.6	$0.1V_{CCO}$	$0.9V_{CCO}$	1.5	-0.5
AGP-1X	-0.3	$0.3V_{CCO}$	$0.5V_{CCO}$	3.6	$0.1V_{CCO}$	$0.9V_{CCO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	0.7	V_{CCO}-1.1	8	-8
SSTL3 class II	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	0.5	V_{CCO}-0.9	16	-16
SSTL2 class I	-0.3	V_{REF}-0.18	V_{REF}+0.18	3.6	0.54	V_{CCO}-0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF}-0.18	V_{REF}+0.18	3.6	0.35	V_{CCO}-0.43	15.2	-15.2
CTT 3.3	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	V_{REF}-0.4	V_{REF}+0.4	8	-8
CTT 2.5	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	V_{REF}-0.4	V_{REF}+0.4	8	-8
HSTL class I	-0.3	V_{REF}-0.1	V_{REF}+0.1	3.6	0.4	V_{CCO}-0.4	8	-8
HSTL class III	-0.3	V_{REF}-0.1	V_{REF}+0.1	3.6	0.4	V_{CCO}-0.4	24	-8
GTL+	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	0.6	n/a	36	n/a

1. Software default setting
2. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed 96mA.

sysIO Differential Input DC Electrical Characteristics and Operating Conditions

Symbol	Parameter	Test Conditions	Min	Max
V_{INP} . V_{INM}	LVDS Input voltage	—	0	2.4
V_{THD}	LVDS Differential input threshold	—	±100mV	—
V_{IL}	LVPECL Input Voltage Low	V_{CC} = 3.0 to 3.6V	V_{CC}-1.81	V_{CC}-1.48
		V_{CC} = 3.3V	1.49V	1.83V
V_{IH}	LVPECL Input Voltage High	V_{CC} = 3.0 to 3.6V	V_{CC}-1.17	V_{CC}-0.88
		V_{CC} = 3.3V	2.14V	2.42V

ispMACH 51024VG External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description[1,2,3]	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	Data propagation delay, 5-PT bypass	—	5.0	—	7.5	—	10.0	—	12.0	ns
t_{PD_PTSA}	Data propagation delay, intrasegment path	—	6.0	—	9.0	—	11.5	—	13.5	ns
t_{PD_GLOBAL}	Data propagation delay, intersegment path	—	6.5	—	9.75	—	13.0	—	16.0	ns
t_S	GLB register setup time before clock, 5-PT bypass	3.0	—	5.0	—	7.5	—	9.3	—	ns
t_{S_PTSA}	GLB register setup time before clock	3.0	—	6.0	—	8.5	—	10.0	—	ns
t_{SIR}	GLB register setup time before clock, input register path	2.8	—	3.0	—	4.0	—	5.0	—	ns
t_H	GLB register hold time before clock, 5-PT bypass	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{H_PTSA}	GLB register hold time before clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time before clock, input reg. path	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	4.4	—	5.0	—	6.0	—	7.0	ns
t_R	External reset pin to output delay	—	6.5	—	9.0	—	10.0	—	10.9	ns
t_{RW}	External reset pulse duration	4.0	—	6.0	—	8.0	—	9.5	—	ns
$t_{LPTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	9.75	—	11.5	—	13.4	ns
$t_{SPTOE/DIS}$	Input to output segment product term output enable/disable	—	8.0	—	11.25	—	17.5	—	20.4	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	6.2	—	7.5	—	8.85	—	10.0	ns
t_{CW}	Global clock width, high or low	1.6	—	2.75	—	3.6	—	4.3	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{WIR}	Input register clock width, high or low	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{SKEW}	Clock-to-out skew, block level	—	0.25	—	0.35	—	0.45	—	0.55	ns
	Clock-to-out skew, segment level	—	0.4	—	0.5	—	0.6	—	0.7	ns
f_{MAX}[4]	Clock frequency with internal feedback	178.6	—	117.0	—	87.0	—	73.0	—	MHz
f_{MAX} (Ext.)	Clock frequency with external feedback, $1/ (t_{S\_PTSA} + t_{CO})$	135.1	—	90.9	—	69.0	—	58.8	—	MHz
f_{MAX} (Tog.)	Clock frequency max Toggle	312.5	—	181.0	—	138.0	—	116.0	—	MHz

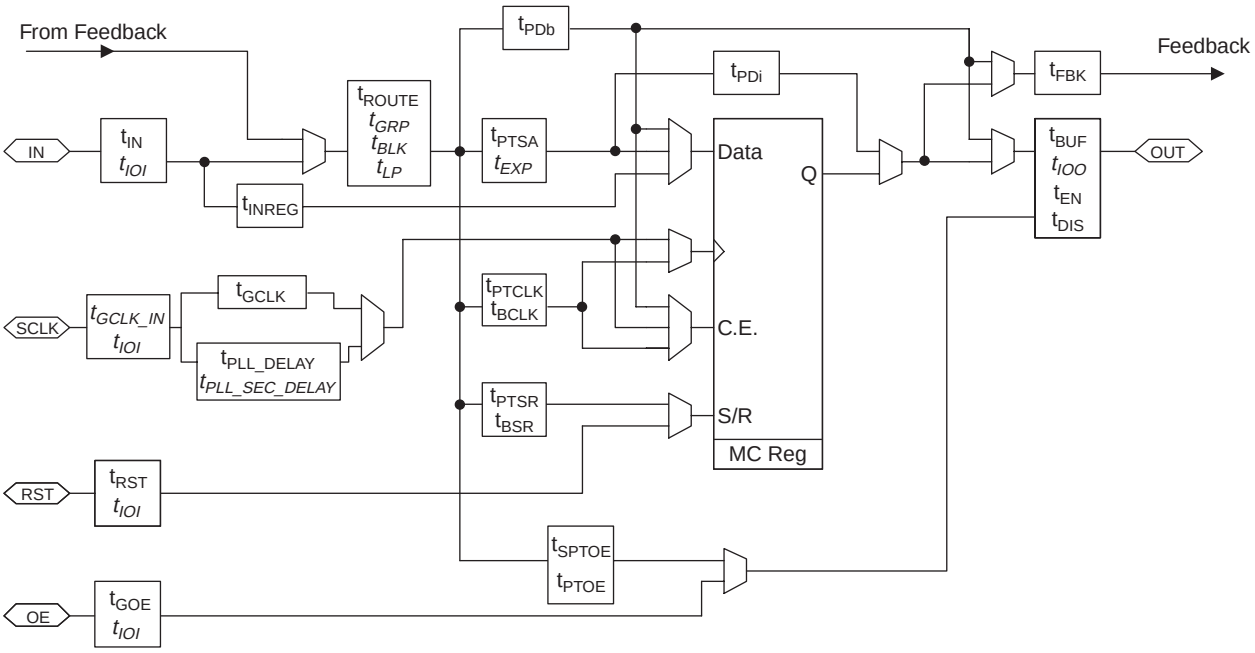
Timing v.1.10

1. Timing numbers are based on default LVCMOS 3.3 I/O Buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, assuming segment and global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using SRP feedback.

Timing Model

The task of determining the timing through the ispMACH 5000VG family, like any CPLD, is relatively simple. The timing model provided in Figure 11 shows the specific delay paths. Once the implementation of a given function is determined either conceptually or from the software report file, the delay path of the function can easily be determined from the timing model. The Lattice design tools report the timing delays based on the same timing model for a particular design. Note that the internal timing parameters are given for reference only, and are not tested. The external timing parameters are tested and guaranteed for every device. For more information on the timing model and usage, please refer to Technical Note TN1001: *ispMACH 5000VG Timing Model Design and Usage Guidelines.*

Figure 11. ispMACH 5000VG Timing Model



Italicized items are optional delay adders

ispMACH 5768VG Internal Timing Parameters (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{BSR}	Block PT Set/Reset Delay	—	2.00	—	3.00	—	4.00	—	4.80	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	2.00	—	3.00	—	4.00	—	4.80	ns
t_{SPTOE}	Segment PT OE Delay	—	2.40	—	3.60	—	7.75	—	9.10	ns
t_{PTOE}	Macrocell PT OE Delay	—	1.40	—	2.10	—	1.75	—	2.10	ns

Notes: Timing v.1.20

1. Internal Timing Parameters are not tested and are for reference only. Refer to Timing Model in this data sheet for further details.
2. t_{PLL_DELAY} is the unit increment by which the clock signal can be incremented. The PLL can adjust the clock signal by up to 3.5ns in either direction in units of 0.5ns for each step.

ispMACH 51024VG Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
In/Out Delays										
t_{IN}	Input Buffer Delay	—	0.65	—	0.95	—	1.25	—	1.40	ns
t_{GCLK_IN}	Global Clock Input Buffer Delay	—	0.65	—	0.95	—	1.25	—	1.40	ns
t_{GOE}	Global OE Pin Delay	—	4.05	—	5.00	—	6.00	—	7.00	ns
t_{BUF}	Delay through Output Buffer	—	1.15	—	1.50	—	1.75	—	1.90	ns
t_{EN}	Output Enable Time	—	2.15	—	2.50	—	2.85	—	3.00	ns
t_{DIS}	Output Disable Time	—	2.15	—	2.50	—	2.85	—	3.00	ns
t_{RSTb}	Global RESETbar Pin Delay	—	4.60	—	6.50	—	7.00	—	7.50	ns
Routing Delays										
t_{ROUTE}	Delay through SRP	—	2.80	—	4.20	—	5.65	—	6.90	ns
t_{PTSA}	Product Term Sharing Array Delay	—	0.40	—	1.85	—	2.35	—	2.50	ns
t_{PDB}	5-PT Bypass Propagation Delay	—	0.40	—	0.85	—	1.35	—	1.80	ns
t_{PDi}	Macrocell Propagation Delay	—	1.00	—	0.50	—	0.50	—	0.80	ns
t_{INREG}	Input Buffer to Macrocell Register Delay	—	3.00	—	3.05	—	3.50	—	4.40	ns
t_{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	—	0.00	ns
t_{GCLK}	Global Clock Tree Delay	—	0.85	—	0.70	—	0.55	—	0.65	ns
t_{PLL_DELAY}	Programmable PLL Delay Increment	—	0.50	—	0.50	—	0.50	—	0.50	ns
$t_{PLL\_SEC\_DELAY}$	Additional Delay When Using Secondary PLL Output	—	0.60	—	0.60	—	0.60	—	0.60	ns
t_{GRP}	Global Routing Pool Delay	—	1.50	—	2.25	—	3.00	—	4.00	ns
Register/Latch Delays										
t_{S}	D-Register Setup Time	0.65	—	0.65	—	1.05	—	1.25	—	ns
t_{S_PT}	D-Register Setup Time with PT Clock	0.65	—	0.65	—	1.05	—	1.25	—	ns
t_{H}	D-Register Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t_{ST}	T-Register Setup Time	1.15	—	1.15	—	1.55	—	1.75	—	ns
t_{ST_PT}	T-Register Setup Time with PT Clock	1.15	—	1.15	—	1.55	—	1.75	—	ns
t_{HT}	T-Register Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t_{COi}	Register Clock to Output/Feedback MUX Time	—	1.75	—	1.85	—	2.45	—	3.05	ns

ispMACH 51024VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
LVDS_in	t_{GCLK_IN}	Using LVDS standard	—	1.70	—	1.70	—	1.70	—	1.70	ns
LVPECL_in	t_{GCLK_IN}	Using LVPECL standard	—	2.10	—	2.10	—	2.10	—	2.10	ns
t_{IOO} Output Adders											
LVCMOS18_4mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 4mA Buffer	—	3.00	—	3.00	—	3.00	—	3.00	ns
LVCMOS18_5mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 5.33mA Buffer	—	2.50	—	2.50	—	2.50	—	2.50	ns
LVCMOS18_8mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 8mA Buffer	—	1.85	—	1.85	—	1.85	—	1.85	ns
LVCMOS18_12mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 12mA Buffer	—	1.35	—	1.35	—	1.35	—	1.35	ns
LVCMOS25_4mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVCMOS25_5mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVCMOS25_8mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 8mA Buffer	—	0.70	—	0.70	—	0.70	—	0.70	ns
LVCMOS25_12mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 12mA Buffer	—	0.50	—	0.50	—	0.50	—	0.50	ns
LVCMOS25_16mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 16mA Buffer	—	0.25	—	0.25	—	0.25	—	0.25	ns
LVCMOS33_4mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVCMOS33_5mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVCMOS33_8mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 8mA Buffer	—	0.40	—	0.40	—	0.40	—	0.40	ns
LVCMOS33_12mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 12mA Buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVCMOS33_16mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 16mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS33_20mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 20mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVTTL	t_{BUF}, t_{EN}, t_{DIS}	Output configured as LVTTL Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
Slow Slew	t_{BUF}, t_{EN}	Output configured for slow slew rate	—	1.50	—	1.50	—	1.50	—	1.50	ns
PCI_out	t_{BUF}, t_{EN}, t_{DIS}	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_out	t_{BUF}, t_{EN}, t_{DIS}	Using PCI-X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_out	t_{BUF}, t_{EN}, t_{DIS}	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL3_I standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
SSTL3_II_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL3_II standard	—	-0.35	—	-0.35	—	-0.35	—	-0.35	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.10

ispMACH 51024VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
SSTL2_I_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL2_I standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL2_II_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL2_II standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
CTT33_out	t_{BUF}, t_{EN}, t_{DIS}	Using CCT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_out	t_{BUF}, t_{EN}, t_{DIS}	Using CCT2.5 standard	—	0.25	—	0.25	—	0.25	—	0.25	ns
HSTL_I_out	t_{BUF}, t_{EN}, t_{DIS}	Using HSTL_I standard	—	-0.30	—	-0.30	—	-0.30	—	-0.30	ns
HSTL_III_out	t_{BUF}, t_{EN}, t_{DIS}	Using HSTL_III standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
GTL+_out	t_{BUF}, t_{EN}, t_{DIS}	Using GTL+ standard	—	0.30	—	0.30	—	0.30	—	0.30	ns

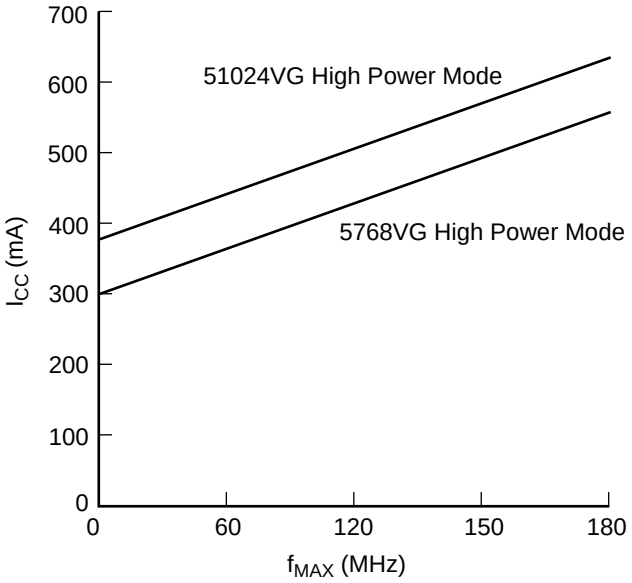
Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.10

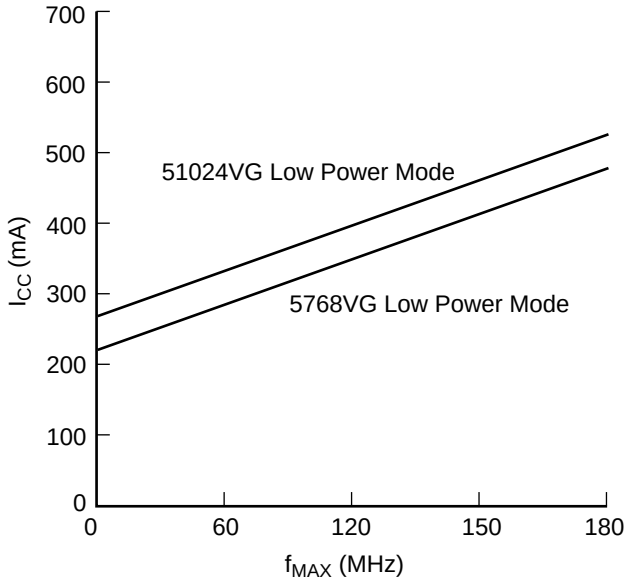
Power Consumption

ispMACH 5000VG Typical Power vs. Frequency

ispMACH 5000VG I_{CC} Curves at High Power Mode



ispMACH 5000VG I_{CC} Curves at Low Power Mode



Note: The devices are configured with maximum number of 16-bit counters, no PLL, typical current at 3.3V, 25° C.

Power Estimation Coefficients

Device	K0	K1	K2	K3	K4	K5	K6	I_{DC} (mA)	I_{DCO} (mA)
ispMACH 5768VG	0.0014	0.0014	0.054	1.5	0.152	0.105	5.0	65	20
ispMACH 51024VG	0.0014	0.0014	0.054	1.5	0.152	0.105	5.0	80	20

Note: For further information about the use of these coefficients, refer to Technical Note TN1002, *Power Estimation in ispMACH 5000VG Devices*.

K0 = average current per product term in high power/MHz
K1 = average current per product term in low power/MHz
K2 = average current per GRP line/MHz
K3 = average current per PLL/MHz
K4 = DC current per product terms in high power
K5 = DC current per product terms in low power
K6 = Static DC current per PLL
I_{DC} = Static device current with all product terms powered off
I_{DCO} = Static I/O bank current

Icc estimates are based on typical conditions (Vcc = 3.3V, room temperature) and an assumption of one GLB load on average exists. These values are for estimates only. Since the value of Icc is sensitive to operating conditions and the program in the device, the actual Icc should be verified.

ispMACH 5768VG Power Supply and NC Connections[1]

Signal	256-Ball fpBGA[2]	484-Ball fpBGA[2]
V_{CC}	F8, F9, H6, H11, J6, J11, L8, L9	B17, B2, B21, B6, C14, C9, E18, E5, F2, F21, J20, J3, P20, P3, U2, U21, Y14, Y9, AA17, AA2, AA21, AA6
V_{CCO0}	C3, C7, G3	B5, D7, E2, E6, E9, F5, G4, J5
V_{CCO1}	K3, P3, P7	P5, U5, V6, V9, Y3
V_{CCO2}	K14, P10, P14	P18, U18, V14, V17, Y20
V_{CCO3}	C10, C14, G14	B18, D16, E14, E17, E21, F18, G19, J18
V_{CCP0}	H1	L7
V_{CCP1}	H16	N18
V_{CCJ}	J1	P4
V_{REF0}	E7	A9
V_{REF1}	M7	AA10
V_{REF2}	R13	AA13
V_{REF3}	A8	A15
GND PLL 0	H7	L6
GND PLL 1	J10	L16
GND	A1, C5, C12, E3, E14, G7, G8, G9, G10, H8, H9, H10, J7, J8, J9, K7, K8, K9, K10, M3, M14, P5, P12	A1, A22, C3, C20, D4, D19, E7, E16, G5, G7, G8, G9, G10, G11, G12, G13, G14, G15, G16, G18, H7, H8, H9, H10, H11, H12, H13, H14, H15, H16, J7, J8, J9, J10, J11, J12, J13, J14, J15, J16, K7, K8, K9, K10, K11, K12, K13, K14, K15, K16, L8, L9, L10, L11, L12, L13, L14, L15, M7, M8, M9, M10, M11, M12, M13, M14, M15, M16, N7, N8, N9, N10, N11, N12, N13, N14, N15, N16, P7, P8, P9, P10, P11, P12, P13, P14, P15, P16, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, T4, T7, T8, T9, T10, T11, T12, T13, T14, T15, T16, T19, W7, W16, AB1, AB22
NC[3]	—	AA1

1. All grounds must be electrically connected at the board level.
2. Not all grounds internally connected within the device.
3. NC pins are not to be connected to any active signals, VCC or GND.

ispMACH 51024 Power Supply and NC Connections[1]

Signal	484-Ball fpBGA[2]	676-Ball fpBGA[2]
V_{CC}	B17, B2, B21, B6, C14, C9, E18, E5, F2, F21, J20, J3, P20, P3, U2, U21, Y14, Y9, AA17, AA2, AA21, AA6	B29, D6, D10, D12, D19, D21, D25, F4, F27, K4, K27, M4, M27, W4, W27, AA4, AA27, AE4, AE27, AG6, AG10, AG12, AG19, AG21,AG25, AJ2
V_{CCO0}	B5, D7, E2, E6, E9, F5, G4, J5	E5, E7, E9, E11, F10, G5, J5, K6, L5
V_{CCO1}	P5, U5, V6, V9, Y3	Y5, AA6, AB5, AD5, AE10, AF5, AF7, AF9, AF11
V_{CCO2}	P18, U18, V14, V17, Y20	Y26, AA25, AB26, AD26, AE21, AF20, AF22, AF24, AF26
V_{CCO3}	B18, D16, E14, E17, E21, F18, G19, J18	E20, E22, E24, E26, F21, G26, J26, K25, L26
V_{CCP0}	L7	P5
V_{CCP1}	N18	N26
V_{CCJ}	P4	U6
V_{REF0}	A9	C11
V_{REF1}	AA10	AK10
V_{REF2}	AA13	AJ21
V_{REF3}	A15	E19
GND PLL 0	L6	R6
GND PLL 1	L16	P25
GND	A1, A22, C3, C20, D4, D19, E7, E16, G5, G7, G8, G9, G10, G11, G12, G13, G14, G15, G16, G18, H7, H8, H9, H10, H11, H12, H13, H14, H15, H16, J7, J8, J9, J10, J11, J12, J13, J14, J15, J16, K7, K8, K9, K10, K11, K12, K13, K14, K15, K16, L8, L9, L10, L11, L12, L13, L14, L15, M7, M8, M9, M10, M11, M12, M13, M14, M15, M16, N7, N8, N9, N10, N11, N12, N13, N14, N15, N16, P7, P8, P9, P10, P11, P12, P13, P14, P15, P16, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, T4, T7, T8, T9, T10, T11, T12, T13, T14, T15, T16, T19, W7, W16, AB1, AB22	A1, A30, B2,C3, C28, D8, D23, F7, F9, F11, F12, F19, F20, F22, F24, G6, G25, H4, H27, J6, J25, L6, L11, L12, L13, L14, L15, L16, L17, L18, L19, L20, L25, M6, M11, M12, M13, M14, M15, M16, M17, M18, M19, M20, M25, N11, N12, N13, N14, N15, N16, N17, N18, N19, N20, P11, P12, P13, P14, P15, P16, P17, P18, P19, P20, R11, R12, R13, R14, R15, R16, R17, R18, R19, R20, T11, T12, T13, T14, T15, T16, T17, T18, T19, T20, U11, U12, U13, U14,U15, U16, U17, U18, U19, U20, V11, V12, V13, V14, V15, V16, V17, V18, V19, V20, W6, W11, W12, W13, W14, W15, W16, W17, W18, W19, W20, W25, Y6, Y11, Y12, Y13, Y14, Y15, Y16, Y17, Y18, Y19, Y20, Y25, AB6, AB25, AC4, AC27, AD6, AD25, AE7, AE9, AE11, AE12, AE19, AE20, AE22, AE24, AG8, AG23, AH3, AH28, AK1, AK30
NC[3]	AA1	A14, A15, A16, A17, B14, B15, B16, B17, C13, C14, C15, C16, C17, C18, D13, D14, D15, D16, D17, D18, E13, E14, E15, E16, E17, E18, F13, F14, F15, F16, F17, F18, AE13, AE14, AE15, AE16, AE17, AE18, AF13, AF14, AF15, AF16, AF17, AF18, AG13, AG14, AG15, AG16, AG17, AG18, AH14, AH15, AH16, AH17, AH18, AJ14, AJ15, AJ16, AJ17, AJ18, AK14, AK15, AK16, AK17

1. All grounds must be electrically connected at the board level.
2. Not all grounds internally connected within the device.
3. NC pins are not to be connected to any active signals, VCC or GND.

ispMACH 5768VG Logic Signal Connections (Continued)

Bank No.	Signal	256 fpBGA	484 fpBGA
1	2C-26	T11	AA11
1	2C-28	T12	V12
1	2C-30	R10	AB11
2	3C-30	P9	W12
2	3C-28	R11	Y11
2	3C-26	T13	Y12
2	3C-24	N9	AB12
2	3C-22	M9	U12
2	3C-20	R12	AA12
2	GNDIO2	GND	GND
2	3C-18	P11	Y13
2	3C-16	N10	AB13
2	3C-14	M10	W13
2	3C-12/VREF2	R13	AA13
2	3C-10	T14	U13
2	3C-8	R14	AB14
2	3C-6	M11	V13
2	3C-4	N11	AA14
2	3C-2	P13	U14
2	3C-0	T15	AB15
2	3D-30	T16	Y15
2	3D-28	N12	AB16
2	GNDIO2	GND	GND
2	3D-26	NC	AA15
2	3D-24	NC	W14
2	3D-22	NC	AB17
2	3D-20	NC	Y16
2	3D-18	NC	AA16
2	3D-16	NC	Y17
2	3D-14	NC	AB18
2	3D-12	NC	V15
2	3D-10	NC	AB19
2	3D-8	NC	W15
2	3D-6	NC	AB20
2	3D-4	NC	AA18
2	GNDIO2	GND	GND
2	3D-2	L10	U15
2	3D-0	L11	W17
2	3A-0	K11	U16
2	3A-2	R15	AA19
2	3A-4	NC	V16
2	3A-6	NC	AB21
2	3A-8	NC	NC

Bank No.	Signal	256 fpBGA	484 fpBGA
2	3A-10	NC	NC
2	GNDIO2	GND	GND
2	3A-12	NC	NC
2	3A-14	NC	NC
2	3A-16	NC	Y18
2	3A-18	P15	W18
2	3A-20	R16	AA20
2	3A-22	P16	W19
2	3A-24	N14	Y19
2	3A-26	N13	V19
2	GNDIO2	GND	GND
2	3A-28	N15	Y21
2	3A-30	N16	W20
2	3B-30	M16	AA22
2	3B-28	M12	W21
2	3B-26	NC	Y22
2	3B-24	NC	V20
2	3B-22	M13	V21
2	3B-20	M15	W22
2	3B-18	L16	V18
2	3B-16	L15	U20
2	3B-14	L13	V22
2	3B-12	L14	U19
2	GNDIO2	GND	GND
2	3B-10	L12	U17
2	3B-8	K13	U22
2	3B-6	K15	T20
2	3B-4	K16	T21
2	3B-2	J16	T17
2	3B-0	K12	R20
3	4B-0	J12	R21
3	4B-2	G16	T22
3	4B-4/PLL_FBK1	G15	P21
3	4B-6/PLL_RST1	H12	N20
3	4B-8	G12	R22
3	4B-10	G13	N21
3	GNDIO3	GND	GND
3	4B-12	F16	M18
3	4B-14	F15	N19
3	4B-16	F13	P22
3	4B-18	F14	M20
3	4B-20	F12	N22
3	4B-22	E16	N17

ispMACH 5768VG Logic Signal Connections (Continued)

Bank No.	Signal	256 fpBGA	484 fpBGA
3	4B-24	G11	M19
3	4B-26	F11	M21
3	4B-28	F10	L19
3	4B-30/CLK_OUT1	B11	L20
3	GNDIO3	GND	GND
3	4A-30	NC	M17
3	4A-28	NC	M22
3	4A-26	NC	K20
3	4A-24	NC	L18
3	4A-22	NC	L21
3	4A-20	NC	K19
3	4A-18	NC	L22
3	4A-16	NC	K17
3	4A-14	E13	K22
3	4A-12	B12	L17
3	GNDIO3	GND	GND
3	4A-10	E15	K21
3	4A-8	D15	K18
3	4A-6	NC	J17
3	4A-4	NC	J19
3	4A-2	D16	J22
3	4A-0	E12	J21
3	5B-0	NC	H19
3	5B-2	NC	H20
3	5B-4	NC	H17
3	5B-6	NC	H18
3	5B-8	NC	H22
3	5B-10	NC	H21
3	GNDIO3	GND	GND
3	5B-12	NC	G20
3	5B-14	NC	G22
3	5B-16	NC	G17
3	5B-18	NC	G21
3	5B-20	NC	F19
3	5B-22	NC	F20
3	5B-24	A16	F22
3	5B-26	B15	E22
3	5B-28	A15	E19
3	5B-30	D13	E20
3	5A-30	B14	D22
3	5A-28	B16	D21
3	GNDIO3	GND	GND
3	5A-26	C16	D20

Bank No.	Signal	256 fpBGA	484 fpBGA
3	5A-24	C15	C22
3	5A-22	D14	C18
3	5A-20	A14	C19
3	5A-18	C13	D17
3	5A-16	B13	C21
3	5A-14	NC	NC
3	5A-12	NC	NC
3	GNDIO3	GND	GND
3	5A-10	NC	NC
3	5A-8	NC	NC
3	5A-6	NC	B22
3	5A-4	NC	D18
3	5A-2	NC	B20
3	5A-0	NC	F17
3	5D-0	NC	B19
3	5D-2	NC	C17
3	GNDIO3	GND	GND
3	5D-4	NC	A21
3	5D-6	NC	D15
3	5D-8	NC	A20
3	5D-10	NC	C16
3	5D-12	NC	A19
3	5D-14	NC	F16
3	5D-16	NC	B16
3	5D-18	NC	D14
3	5D-20	NC	A18
3	5D-22	A13	F15
3	5D-24	A12	A17
3	5D-26	A11	B15
3	GNDIO3	GND	GND
3	5D-28	A10	A16
3	5D-30	C11	F14
3	5C-0	A9	C15
3	5C-2	D12	D13
3	5C-4	D11	E15
3	5C-6	B10	F13
3	5C-8	B9	B14
3	5C-10	E11	E13
3	5C-12/VREF3	A8	A15
3	5C-14	D10	D12
3	5C-16	E10	A14
3	5C-18	A7	B13
3	GNDIO3	GND	GND

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
0	1A-30	K5	M3
0	GNDIO0	GND	GND
0	1B-30/CLK_OUT0	N1	M2
0	1B-28	M2	M1
0	1B-26	P1	N6
0	1B-24	L4	N5
0	1B-22	N2	N4
0	1B-20	M3	N3
0	1B-18	L5	N2
0	1B-16	R1	N1
0	1B-14	P2	P6
0	1B-12	N3	P4
0	GNDIO0	GND	GND
0	1B-10	M6	P3
0	1B-8	M5	P2
0	1B-6/PLL_RST0	M4	P1
0	1B-4/PLL_FBK0	N4	R4
0	1B-2	N6	R3
0	1B-0	N5	R2
1	2B-0	NC	R1
1	2B-2	NC	T1
1	2B-4	NC	T3
1	2B-6	NC	T2
1	2B-8	NC	U1
1	2B-10	NC	U2
1	GNDIO1	GND	GND
1	2B-12	NC	U3
1	2B-14	NC	U4
1	2B-16	NC	V1
1	2B-18	NC	V2
1	2B-20	NC	V3
1	2B-22	NC	V4
1	2B-24	NC	W1
1	2B-26	NC	V6
1	2B-28	NC	W2
1	2B-30	NC	W3
1	GNDIO1	GND	GND
1	2A-30	NC	Y1
1	2A-28	NC	W5
1	2A-26	NC	Y2
1	2A-24	NC	Y3
1	2A-22	NC	AA1
1	2A-20	NC	Y4

Bank No.	Signal	484 fpBGA	676 fpBGA
1	2A-18	NC	AA2
1	2A-16	NC	AA3
1	2A-14	NC	AB1
1	2A-12	NC	AB2
1	GNDIO1	GND	GND
1	2A-10	NC	AA5
1	2A-8	NC	AB3
1	2A-6	NC	AC1
1	2A-4	NC	AB4
1	2A-2	NC	AC2
1	2A-0	NC	AD1
1	3B-0	R5	AC3
1	3B-2	T2	AD2
1	3B-4	T5	AE1
1	3B-6	T3	AD3
1	3B-8	U1	AE2
1	3B-10	U4	AC5
1	GNDIO1	GND	GND
1	3B-12	V1	AF1
1	3B-14	U3	AD4
1	3B-16	V5	AE3
1	3B-18	V2	AC6
1	3B-20	W1	AF2
1	3B-22	V3	AG1
1	3B-24	W2	AF3
1	3B-26	Y1	AG2
1	3B-28	Y2	AH1
1	3B-30	W3	AE5
1	3A-30	AA3	AF4
1	3A-28	W4	AG3
1	GNDIO1	GND	GND
1	3A-26	W5	AE6
1	3A-24	Y4	AH2
1	3A-22	T6	AJ1
1	3A-20	Y5	AG4
1	3A-18	U6	AF6
1	3A-16	AA4	AG5
1	3A-14	NC	AH4
1	3A-12	NC	AJ3
1	GNDIO1	GND	GND
1	3A-10	NC	AK2
1	3A-8	NC	AE8
1	3A-6	W6	AH5

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
3	6A-10	K21	J29
3	6A-8	K18	K26
3	6A-6	J17	J28
3	6A-4	J19	H30
3	6A-2	J22	J27
3	6A-0	J21	H29
3	7B-0	H19	G30
3	7B-2	H20	H28
3	7B-4	H17	G29
3	7B-6	H18	F30
3	7B-8	H22	G28
3	7B-10	H21	H26
3	GNDIO3	GND	GND
3	7B-12	G20	F29
3	7B-14	G22	G27
3	7B-16	G17	E30
3	7B-18	G21	F28
3	7B-20	F19	H25
3	7B-22	F20	E29
3	7B-24	F22	D30
3	7B-26	E22	E28
3	7B-28	E19	D29
3	7B-30	E20	C30
3	7A-30	D22	F26
3	7A-28	D21	E27
3	GNDIO3	GND	GND
3	7A-26	D20	D28
3	7A-24	C22	F25
3	7A-22	C18	C29
3	7A-20	C19	B30
3	7A-18	D17	D27
3	7A-16	C21	E25
3	7A-14	NC	D26
3	7A-12	NC	C27
3	GNDIO3	GND	GND
3	7A-10	NC	B28
3	7A-8	NC	A29
3	7A-6	B22	F23
3	7A-4	D18	C26
3	7A-2	B20	B27
3	7A-0	F17	A28
3	7D-0	B19	A27
3	7D-2	C17	B26

Bank No.	Signal	484 fpBGA	676 fpBGA
3	GNDIO3	GND	GND
3	7D-4	A21	E23
3	7D-6	D15	D24
3	7D-8	A20	C25
3	7D-10	C16	A26
3	7D-12	A19	B25
3	7D-14	F16	C24
3	7D-16	B16	A25
3	7D-18	D14	B24
3	7D-20	A18	C23
3	7D-22	F15	D22
3	7D-24	A17	A24
3	7D-26	B15	E21
3	GNDIO3	GND	GND
3	7D-28	A16	B23
3	7D-30	F14	C22
3	7C-0	C15	A23
3	7C-2	D13	B22
3	7C-4	E15	C21
3	7C-6	F13	A22
3	7C-8	B14	D20
3	7C-10	E13	B21
3	7C-12/VREF3	A15	E19
3	7C-14	D12	C20
3	7C-16	A14	A21
3	7C-18	B13	B20
3	GNDIO3	GND	GND
3	7C-20	A13	A20
3	7C-22	B12	C19
3	7C-24	C13	B19
3	7C-26	A12	A19
3	7C-28	C12	B18
3	7C-30	A11	A18
—	GCLK0	P6	R5
—	GCLK1	R6	T6
—	GCLK2	P17	R25
—	GCLK3	P19	P26
—	GOE0	R18	T26
—	GOE1	R17	R26
—	RESETB	R19	T25
—	TCK	R3	U5
—	TDI	R2	T5
—	TDO	R4	V5

Signal Configuration

ispMACH 5768VG and 51024VG 484-ball fpBGA

	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O / VREF3	I/O	I/O	I/O	I/O	I/O	I/O/ VREF0	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	**A**
B	I/O	VCC	I/O	I/O	VCCO3	VCC	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCC	VCCO0	I/O	I/O	VCC	I/O	**B**
C	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	I/O	GND	I/O	I/O	**C**
D	I/O	I/O	I/O	GND	I/O	I/O	VCCO3	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCCO0	I/O	I/O	GND	I/O	I/O	I/O	**D**
E	I/O	VCCO3	I/O	I/O	VCC	VCCO3	GND	I/O	VCCO3	I/O	I/O	I/O	I/O	VCCO0	I/O	GND	VCCO0	VCC	I/O	I/O	VCCO0	I/O	**E**
F	I/O	VCC	I/O	I/O	VCCO3	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCCO0	I/O	I/O	VCC	I/O	**F**
G	I/O	I/O	I/O	VCCO3	GND	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	GND	VCCO0	I/O	I/O	I/O	**G**
H	I/O	I/O	I/O	I/O	I/O	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O	I/O	I/O	I/O	**H**
J	I/O	I/O	VCC	I/O	VCCO3	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	VCCO0	I/O	VCC	I/O	I/O	**J**
K	I/O	I/O	I/O	I/O	I/O	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O	I/O	I/O	I/O	**K**
L	I/O	I/O	I/O/ CLK_OUT1	I/O	I/O	I/O	GNDP1	GND	GND	GND	GND	GND	GND	GND	GND	VCCP0	GNDP0	I/O	I/O	I/O	I/O	I/O	**L**
M	I/O	I/O	I/O	I/O	I/O	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O/ PLL_RST0	I/O	I/O	I/O	**M**
N	I/O	I/O	I/O/ PLL_RST1	I/O	VCCP1	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O/ PLL_FBK0	I/O	I/O	I/O/ CLK_OUT0	**N**
P	I/O	I/O/ PLL_FBK1	VCC	GCLK3	VCCO2	GCLK2	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GCLK0	VCCO1	VCCJ	VCC	I/O	I/O	**P**
R	I/O	I/O	I/O	RESETB	GOE0	GOE1	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GCLK1	I/O	TDO	TCK	TDI	I/O	**R**
T	I/O	I/O	I/O	GND	TOE	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	GND	I/O	I/O	TMS	**T**
U	I/O	VCC	I/O	I/O	VCCO2	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCCO1	I/O	I/O	VCC	I/O	**U**
V	I/O	I/O	I/O	I/O	I/O	VCCO2	I/O	I/O	VCCO2	I/O	I/O	I/O	I/O	VCCO1	I/O	I/O	VCCO1	I/O	I/O	I/O	I/O	I/O	**V**
W	I/O	I/O	I/O	I/O	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	**W**
Y	I/O	I/O	VCCO2	I/O	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	I/O	VCCO1	I/O	I/O	**Y**
AA	I/O	VCC	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O/ VREF2	I/O	I/O	I/O/ VREF1	I/O	I/O	I/O	VCC	I/O	I/O	I/O	VCC	NC[1]	**AA**
AB	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	**AB**
	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

ispMACH 5768VG and 51024VG 484BGA/51024VG

Bottom View

1. NCs are not to be connected to any active signals, VCC or GND.

Note: Ball A1 indicator dot on top side of package.

Industrial

Part Number	Package	Pin Count	Macrocells	Tpd	Voltage
LC51024VG-75F484I	fpBGA	484	1024	7.5	3.3
LC51024VG-10F484I	fpBGA	484	1024	10	3.3
LC51024VG-12F484I	fpBGA	484	1024	12	3.3
LC51024VG-75F676I	fpBGA	676	1024	7.5	3.3
LC51024VG-10F676I	fpBGA	676	1024	10	3.3
LC51024VG-12F676I	fpBGA	676	1024	12	3.3
LC5768VG-75F256I	fpBGA	256	768	7.5	3.3
LC5768VG-10F256I	fpBGA	256	768	10	3.3
LC5768VG-12F256I	fpBGA	256	768	12	3.3
LC5768VG-75F484I	fpBGA	484	768	7.5	3.3
LC5768VG-10F484I	fpBGA	484	768	10	3.3
LC5768VG-12F484I	fpBGA	484	768	12	3.3

Note: the ispMACH 5000VG family is dual-marked with both Commercial and Industrial grades. The Commercial speed grade is one speed grade faster (i.e. LC51024VG-75F484C) than the Industrial speed grade (i.e. LC51024VG-10F484I).

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 5000VG family:

- *ispMACH 5000VG sysIO Design and Usage Guidelines* (TN1000)
- *ispMACH 5000VG Timing Model Design and Usage Guidelines* (TN1001)
- *Power Estimation in ispMACH 5000VG Devices* (TN1002)
- *ispMACH 5000VG PLL Usage Guidelines* (TN1003)